

Title (en)

Chip board panel, method and apparatus of manufacturing the panel

Title (de)

OSB-Platte sowie Verfahren und Vorrichtung zu ihrer Herstellung

Title (fr)

Plaque composite en bois, procédé et appareil pour la fabrication de la plaque

Publication

**EP 1721715 A1 20061115 (DE)**

Application

**EP 06007021 A 20060401**

Priority

DE 102005021903 A 20050512

Abstract (en)

The method involves arranging wood chips or wood fibers glued with resin in several layers (6, 7, 8) to form a splinter or fiber cake and pressing the wood chips or wood fibers together by applying pressure and temperature. At least one layer material insert (4, 5), in particular a fleece, a fabric, plastic or paper insert, is introduced between the layers before pressing and is pressed with the wood fibers or wood chips. Independent claims are also included for the following: (A) a wood material board (B) and a device for manufacturing a wood material board .

IPC 8 full level

**B27N 3/06** (2006.01)

CPC (source: EP)

**B27N 3/06** (2013.01); **B27N 3/14** (2013.01)

Citation (search report)

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Designated contracting state (EPC)

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Designated extension state (EPC)

AL BA HR MK YU

DOCDB simple family (publication)

**EP 1721715 A1 20061115; EP 1721715 B1 20100818**; AT E477897 T1 20100915; DE 102005021903 A1 20061116; DE 102005021903 B4 20080710; DE 502006007671 D1 20100930; ES 2349871 T3 20110112; PL 1721715 T3 20110228

DOCDB simple family (application)

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